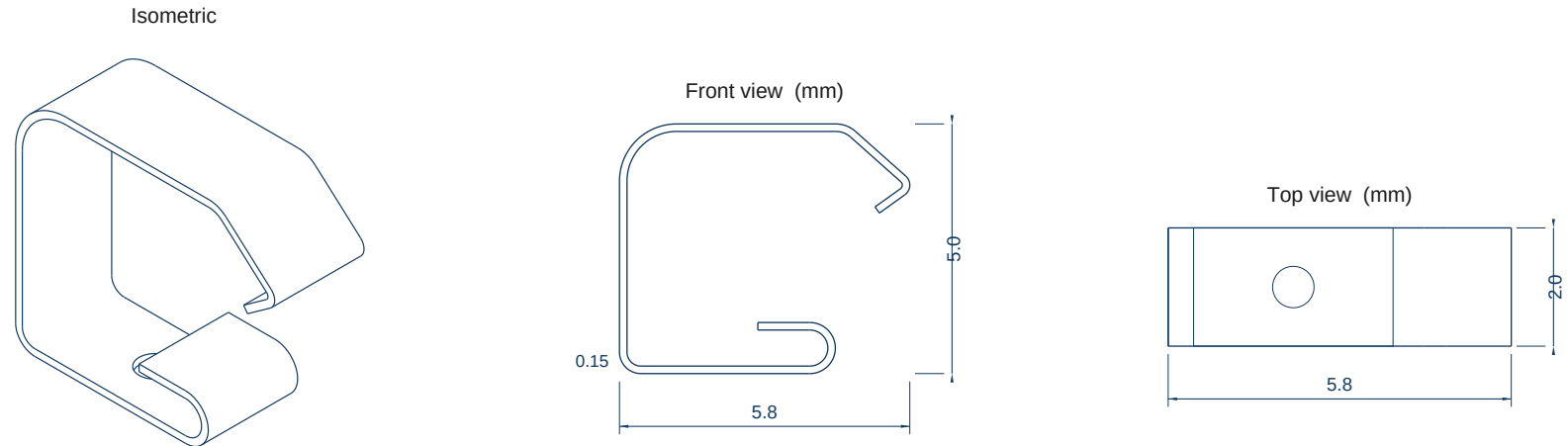




Type C-09 BC09-20058050

SMD EMI Spring Contact | Beryllium Copper | Units: mm



MECHANICAL	VALUE
Thickness	0.15 mm
Width	2.0 mm +/- 0.2
Length	5.8 mm +/- 0.2
Height	5.0 mm +/- 0.2
Form	C-clip: base + return tongue, back wall, top arm + folded tip
Base curl	R0.435 CL, 180 deg
Corners	R0.355 CL base / R1.066 CL top, 90 deg
Arm bend / tip fold	R0.514 CL, 42 deg / R0.165 CL, 103 deg
Return tongue	1.04 mm
Base hole	dia 0.70 mm, centred in the base
Developed length	17.25 mm
Material / plating	BeCu, Gold-plated (G)
Volume / mass	5.116 mm ³ 42.8 mg (BeCu)

PRODUCT DATA	VALUE
Mfr P/N	BC09-20058050G-SY (Au)
Brand	Seyunda
Description	SMD EMI Contact 5.8x2.0x5.0mm Au
Packaging	Tape & Reel (TR)
Category	Connectors, Interconnects
Sub-category	Contacts, Spring Loaded (Pogo Pins), and Pressure
Lifecycle / origin	Active / Taiwan, Republic of China
RoHS / REACH	RoHS3 Compliant / REACH Unaffected
ECCN / ESD	EAR99 / Static sensitive: Yes
Datasheet	seyunda.com/datasheet/Seyunda-SMD-Spring-Contacts-Datasheet.pdf
Product page	seyunda.com/type-c-09.html
File format	STEP AP214